

**METHOD OF FORMING AN ADHESION LAYER WITH AN
ELEMENT REACTIVE WITH A BARRIER LAYER**

ABSTRACT OF THE DISCLOSURE

An exemplary embodiment is related to a method of using an adhesion precursor in an integrated circuit fabrication process. The method includes providing a gas of material over a dielectric material and providing a copper layer over an adhesion precursor layer. The adhesion precursor layer is formed by the gas, and the dielectric material includes an aperture.